

SOT1883-1

plastic, thermal enhanced super thin quad flat package; no leads; 16 terminals; body 2.6 x 2.6 x 0.35 mm

6 July 2016

Package information

1. Package summary

| | |
|--|--|
| Dimensions (mm) | 2.6 x 2.6 x 0.35 |
| Terminal position code | B (bottom) |
| Package type descriptive code | HX2QFN16 |
| Package outline version code | SOT1883-1 |
| Manufacturer package code | SOT1883 |
| Package type industry code | HX2QFN |
| Package outline version description | plastic, thermal enhanced super thin quad flat package; no leads; 16 terminals; body 2.6 x 2.6 x 0.35 mm |
| Package style descriptive code | HXQFN (thermal enhanced extremely thin quad flatpack; no leads) |
| Package body material type | X |
| Mounting method type | S (surface mount) |
| Package life cycle status | REL |
| Security status | COMPANY PUBLIC |
| Issue date | 16-6-2016 |
| Customer specific indicator | N |
| Maturity | Product |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|--------|----------------|-----|-----|------|-----|------|
| A | seated height | 0.3 | - | 0.35 | 0.4 | mm |
| D | package length | 2.5 | - | 2.6 | 2.7 | mm |
| E | package width | 2.5 | - | 2.6 | 2.7 | mm |
| e | nominal pitch | - | - | 0.4 | - | mm |



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2. Package outline

HX2QFN16: plastic, thermal enhanced super thin quad flat package; no leads; 16 terminals; body 2.6 x 2.6 x 0.35 mm

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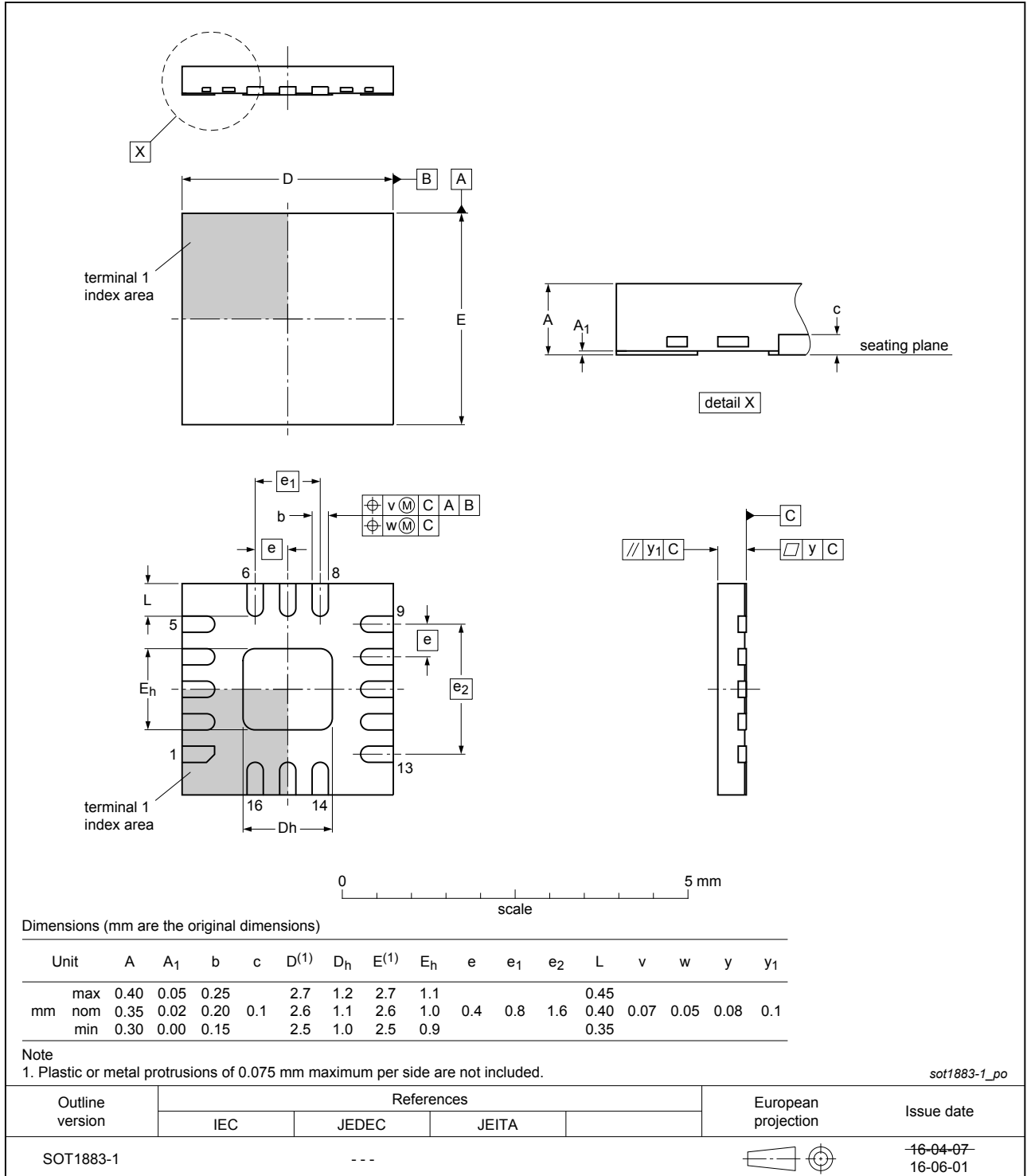


Fig. 1. Package outline HX2QFN (SOT1883-1)

3. Legal information

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